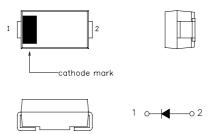
Nihon Inter Electronics Corporation

SBD Type: EC10QS03L

FEATURES

- * Miniature Size, Surface Mount Device
- * Extremely Low Forward Voltage Drop
- * Low Power Loss, High Efficiency
- * High Surge Capability
- * 30 Volts through 100Volts Types Available
- * Packaged in 12mm Tape and Reel
- * Not Rolling During Assembly

OUTLINE DRAWING



Maximum Ratings

Approx Net Weight:0.06g

Rating	Symbol	EC10QS03L				
Repetitive Peak Reverse Voltage	V _{RRM}	30				
Average Rectified Output Current	Io	1.0	Ta=28 °C *1	50Hz Half Sine	Α	
		1.0	Ta=58 °C *2	Wave Resistive Load	A	
RMS Forward Current	I _{F(RMS)}	1.57				
Surge Forward Current	I _{FSM}	20	50Hz Half Sine Wa	A		
		2.0	Non-repetitive			
Operating JunctionTemperature Range	T_{jw}	-40 to +150				
Storage Temperature Range	T_{stg}	-40 to +150				

Electrical • Thermal Characteristics

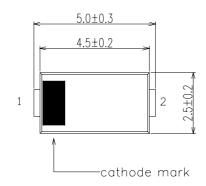
Characteristics	Symbol	Conditions	Min.	Тур.	Max.	Unit	
Peak Reverse Current	I_{RM}	Tj= 25°C, V _{RM} = V _{RRM}		-	-	1.0	mA
Peak Forward Voltage	V_{FM}	Tj= 25°C, I _{FM} = 1.0A		-	-	0.45	V
Thermal Resistance	Rth _(j-a)	Junction to Ambient	*1	-	ı	157	°C /W
			*2	-	-	108	

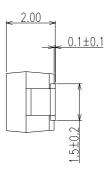
^{*1} Glass Epoxy Substrate Mounted

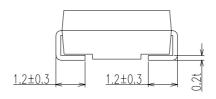
^{*2} Alumina Substrate Mounted Soldering Lands=2x2mm,Both Sides

Nihon Inter Electronics Corporation

EC10QS03L OUTLINE DRAWING (Dimensions in mm)









SOLDERING PAD

